



Material Content Data Sheet



Sales Product Name	IGD01N120H2	Issued	24. February 2022
MA#	MA005700837		
Package	PG-TO252-3-11	Weight*	363.86 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.044	0.29	0.29	2870	2870
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		178	
	non noble metal	iron	7439-89-6	0.215	0.06		592	
	non noble metal	copper	7440-50-8	215.017	59.07	59.15	590936	591706
wire	non noble metal	aluminium	7429-90-5	0.113	0.03	0.03	310	310
encapsulation	organic material	carbon black	1333-86-4	1.232	0.34		3386	
	inorganic material	antimonytrioxide	1309-64-4	2.464	0.68		6772	
	plastics	brominated resin	-	2.464	0.68		6772	
	plastics	epoxy resin	-	24.641	6.77		67721	
	inorganic material	silicondioxide	60676-86-0	92.404	25.40	33.87	253955	338606
leadfinish	non noble metal	tin	7440-31-5	3.740	1.03	1.03	10279	10279
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	250	251
solder	non noble metal	tin	7440-31-5	0.023	0.01		64	
	noble metal	silver	7440-22-4	0.029	0.01		80	
	non noble metal	lead	7439-92-1	1.113	0.31	0.33	3059	3203
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			16	
	non noble metal	iron	7439-89-6	0.019	0.01		53	
	non noble metal	copper	7440-50-8	19.177	5.27	5.28	52706	52775
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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